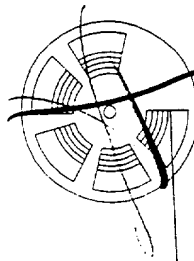
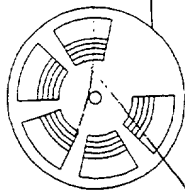


[illegible]

~~COF is a Reel to Reel Process~~



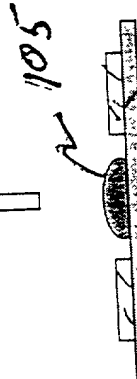
TI-325018



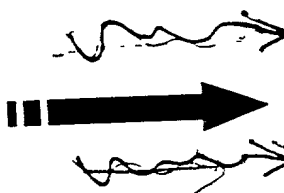
Side View



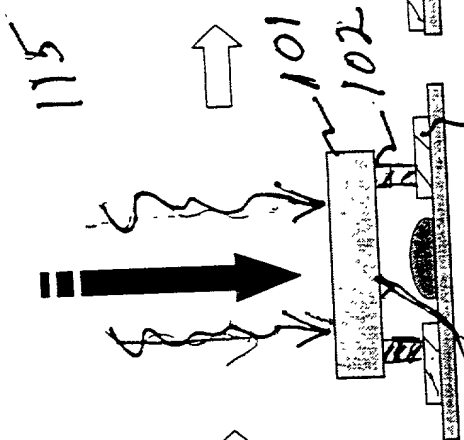
103 104
FIGURE 1a
~~NCP DISCENSE~~



NCP Disbense



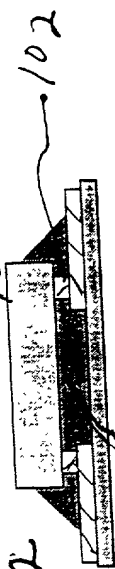
111
FIGURE 16
~~ILB Binding~~



—

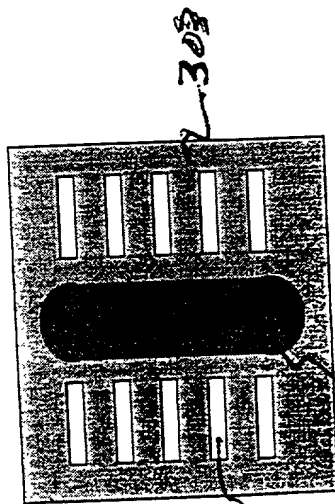


FIGURE



Assembly Complete

TT-32508



206 FIC4RB32

~~Top View~~

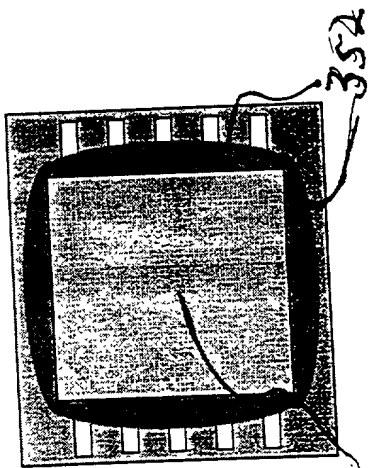


Figure 3b

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TEST 206200T



time + temperature
(Prior Act)

Figure 2

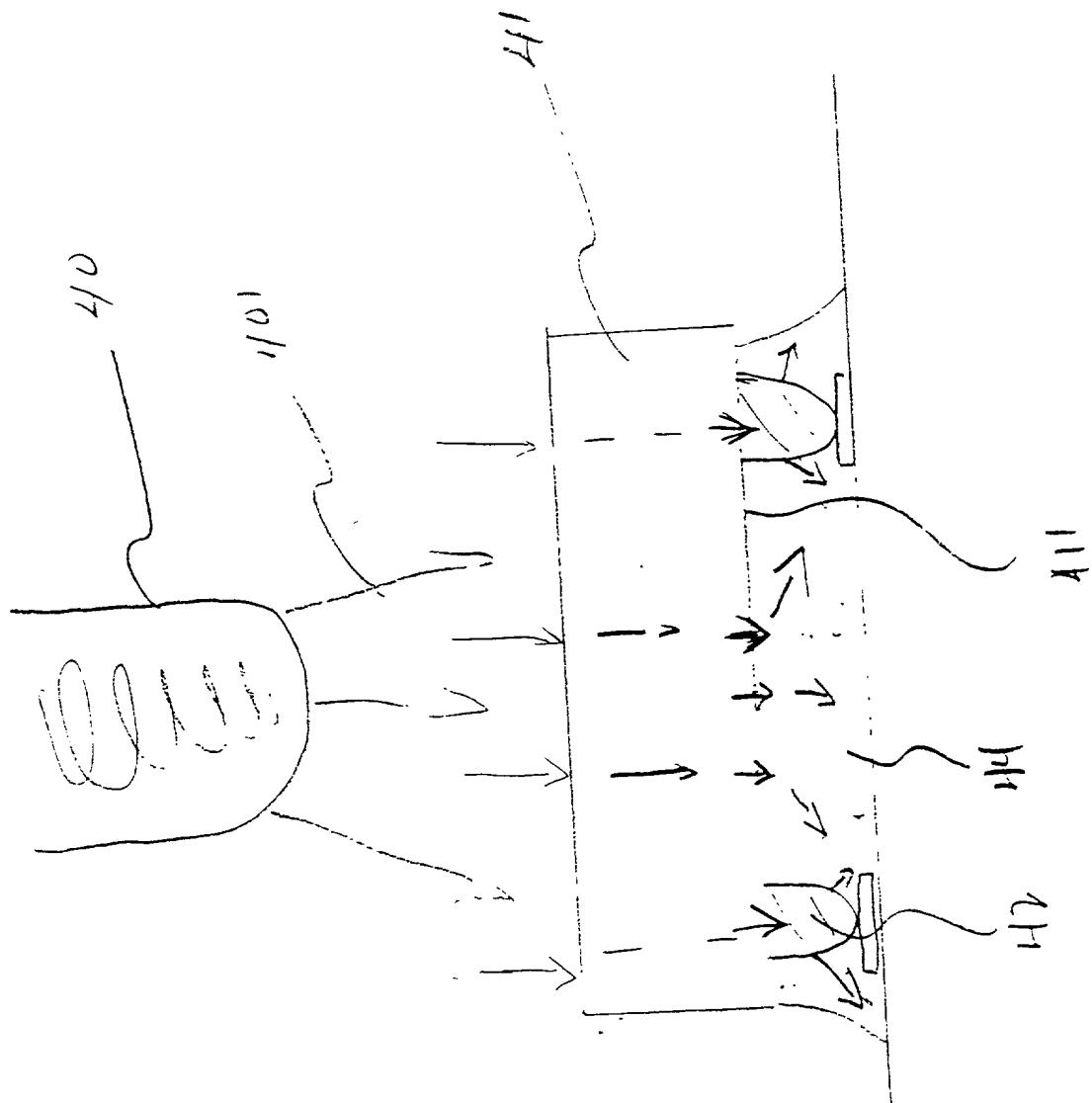
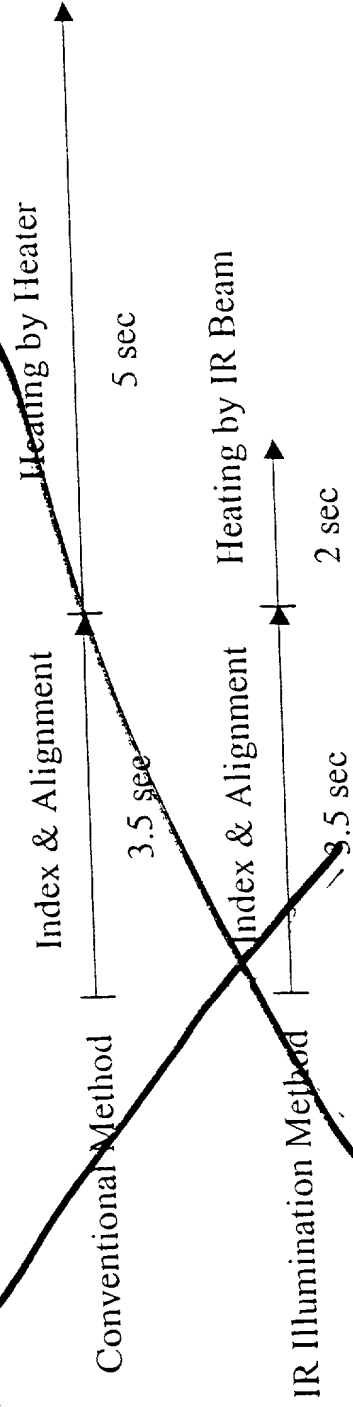


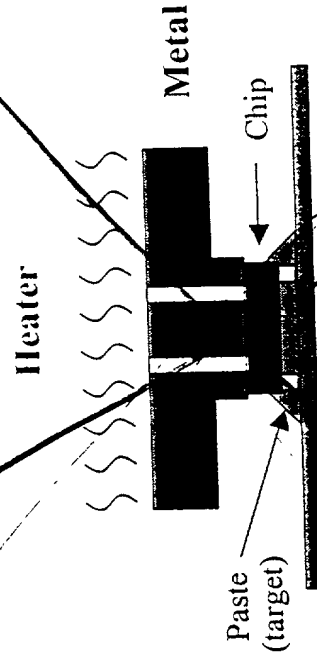
FIGURE 1

Improve 40% Total Cycle Time :



Principles :

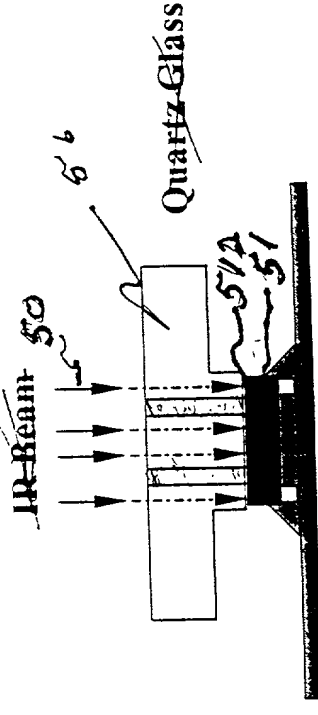
Conventional



Chip (silicon) is a low thermal conductivity interface. It takes time to transfer heat to target through silicon.

IR Illumination

FIGURE 5



Quartz glass with 60% transmission rate by IR beam. Heating energy of IR illumination can be absorbed by epoxy easily to reduce heating time.

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TI Taiwan 2000 Annual Policy Deployment
~~CONV-Bond Heating Method~~

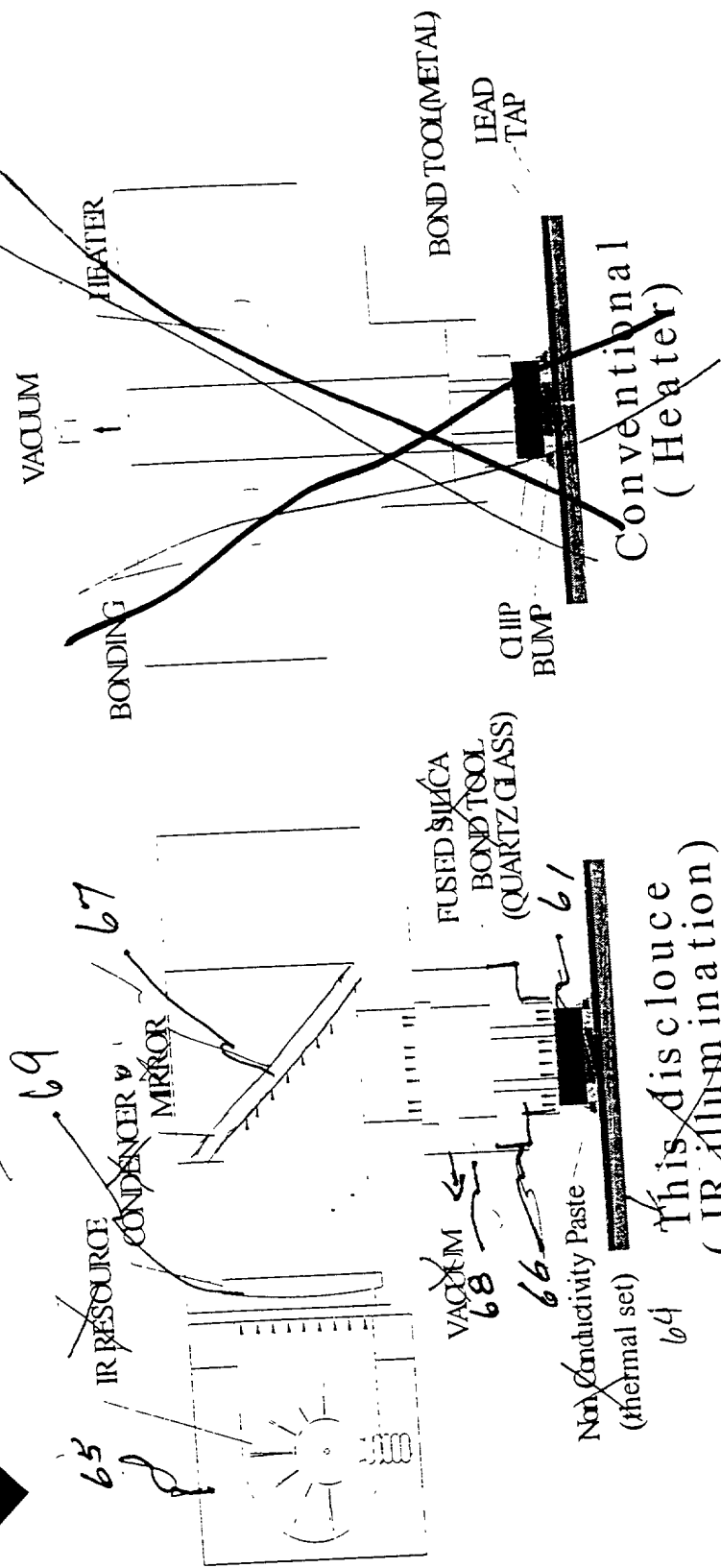


FIGURE 6

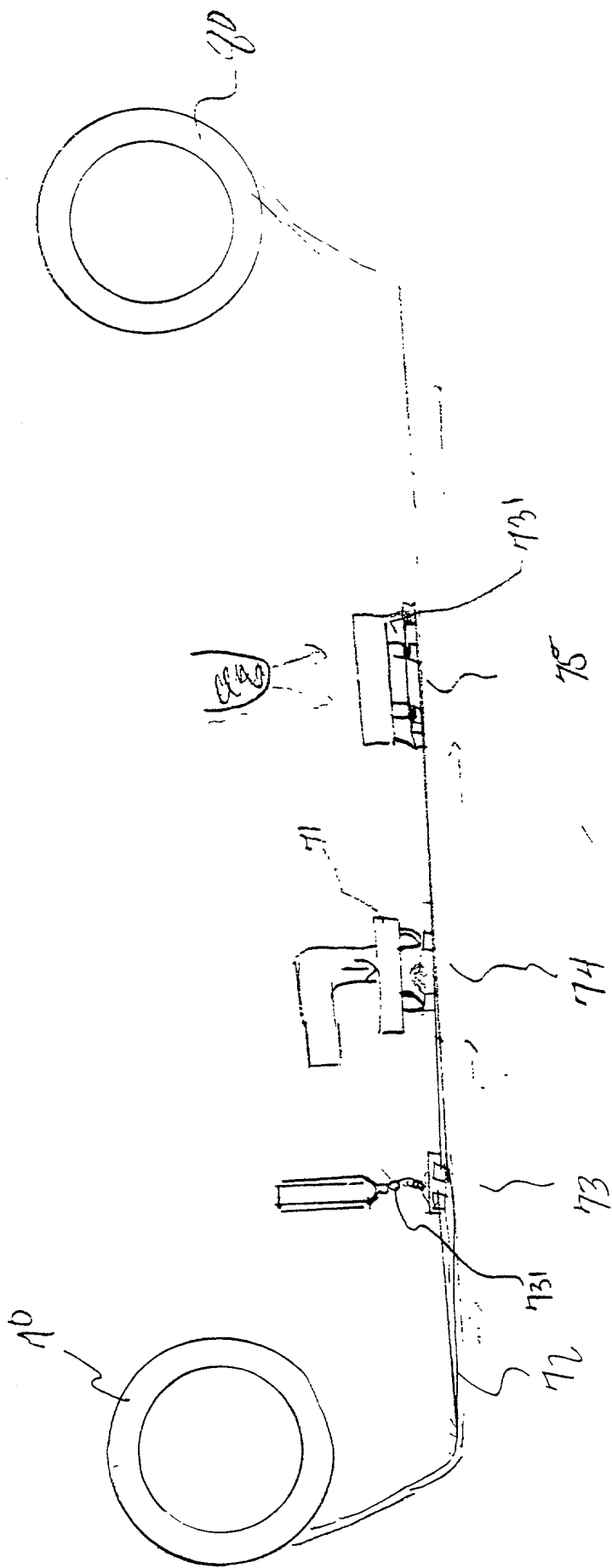


Fig 7